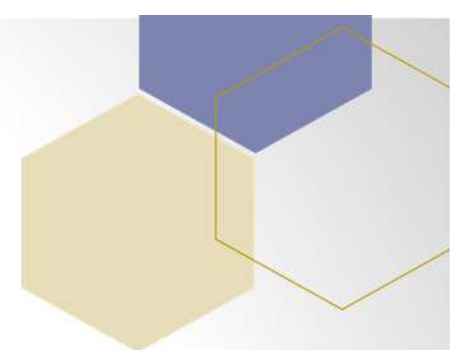
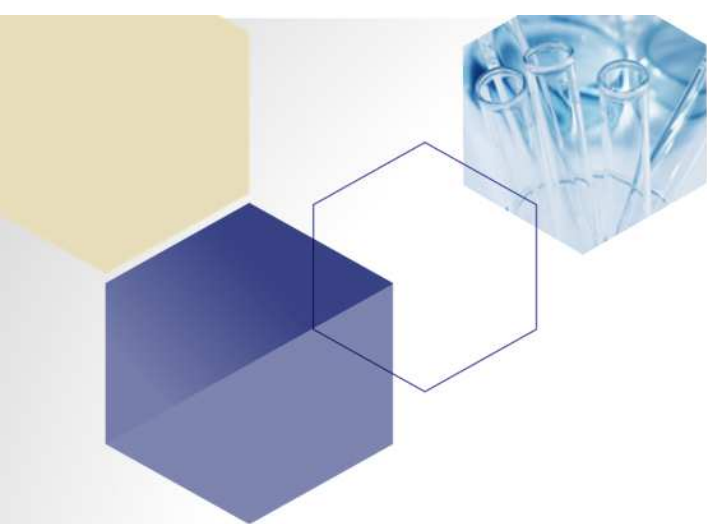




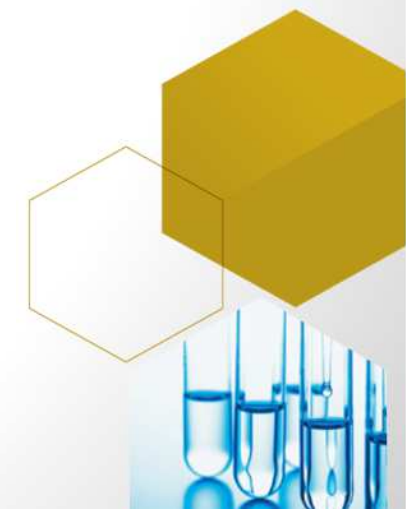
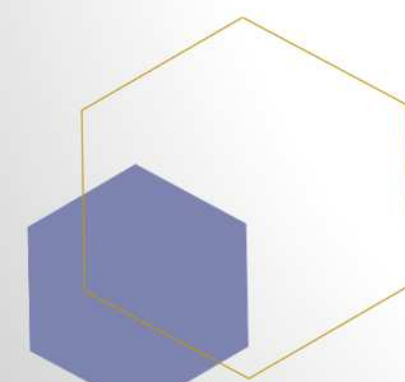
Interim Financial Results for the Six Months Ended September 30, 2026

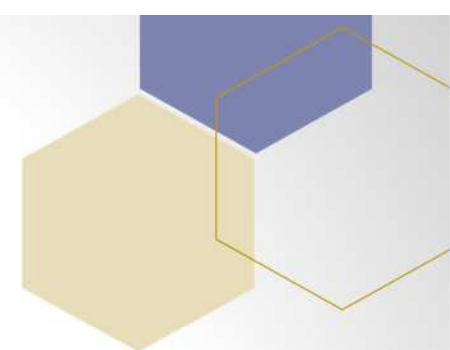
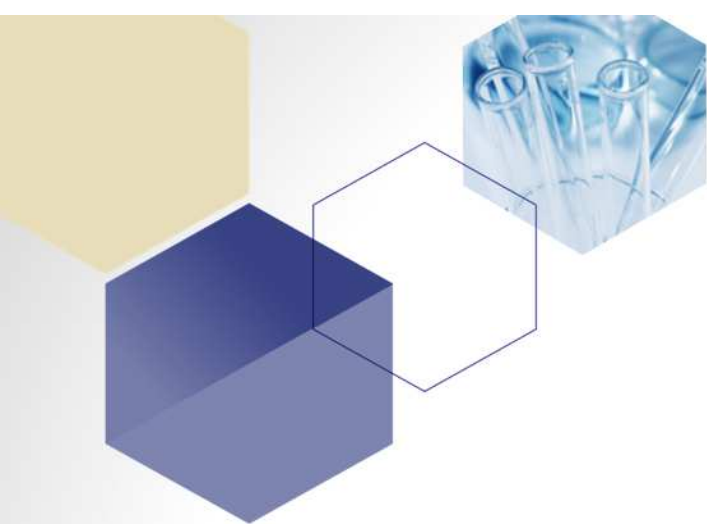


JAPAN PURE CHEMICAL CO.,LTD.

Securities Code: 4973

October 27, 2026





Summary of Financial Results

Key points on how to read the Company's business results

- Sales vary significantly between selling noble metals with chemicals and selling chemicals alone.
- Noble metals have a significant impact on sales because they are expensive and their prices fluctuate.

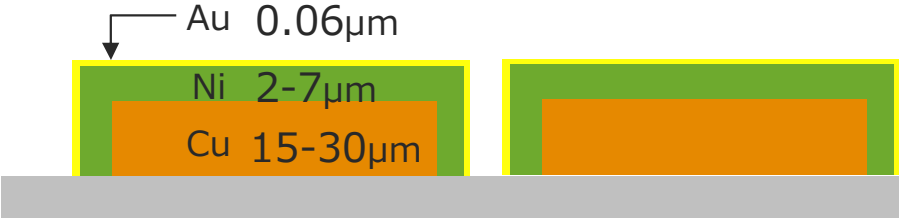
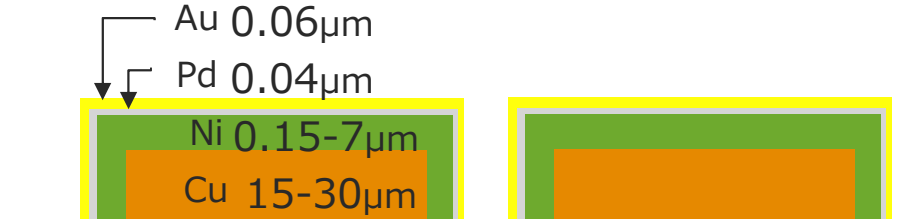
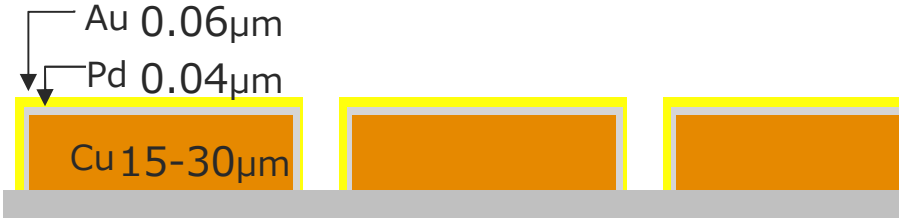
Plating Method

Term	Applications	Features
Electrolytic plating	—	Plating method on metal surfaces with electric current
Pure gold plating	Printed circuit boards (CPU, GPU, etc.) for PCs, smartphones, etc.	High-purity gold plating
Hard gold plating	Connectors for smartphones, automotive, industrial machinery, etc.	Gold plating that is hardened with alloy components
Palladium (Pd) plating	Lead frames for PCs, automotive, industrial machinery, etc.	Used as an undercoat for gold plating. PPF stands for Pre Plated Lead frame.
Electroless plating	—	Plating method by chemical reaction without electric current
Immersion plating	Semiconductor memory(DRAM, NAND) Substrates with semiconductors for servers, PCs, smart phones, etc.	Plating method for forming by replacing metal on surface by utilizing solubility (ionization tendency) of each metal
Auto catalytic plating(Au)	Semiconductor Mounted Substrate CPU, GPU, etc. for servers, PCs, etc.	Plating method capable of forming thick coatings by utilizing chemical reaction with reducing agents
Auto catalytic plating(Pd)	Semiconductor Mounted Substrate for PC, server	Plating method capable of forming thick coatings by utilizing chemical reaction with reducing agents used as a base for gold plating

Product Lineup

Plating Methods		Applications	Product Lineup	
Electrolytic plating	Pure gold		1. Pure gold plating enabling uniform coating even on rough surfaces 2. Pure gold plating with higher hardness	TEMPERESIST Series
	Hard gold (Alloy)		Gold saving hard gold plating for micro connectors: OROBRGHT BAR7	OROBRIGHT BAR7
	Palladium (Pd)		Palladium plating for thin coating applicable to PPF: PALLABRIGHT NANO2	PALLABRIGHT NANO2
Electroless plating	Immersion gold		Immersion gold plating compatible with mid- to high-P Ni: IM-GOLD IB2X Immersion gold plating with less Ni corrosion: IM-GOLD CN Immersion gold plating without Ni plating: IM-GOLD PC	IM-GOLD IB2X IM-GOLD CN IM-GOLD PC
	Auto catalytic gold		Auto catalytic gold plating for thin coating using gold sulfite: HY-GOLD Auto catalytic gold plating for thin coating using gold cyanide: HY-GOLD CN	HY-GOLD HY-GOLD CN
	Auto catalytic palladium		Auto catalytic palladium plating for ENEPIG: NEO PALLABRIGHT 2 Direct auto catalytic palladium plating: NEO PALLABRIGHT DP	NEO PALLABRIGHT 2 NEO PALLABRIGHT DP
Peripheral fields			Base metals (copper, tin, nickel) Alloy plating, Post-treatment agents	

Plating Process Description

Term	Description	Composition of plating
ENIG	Electroless Nickel Immersion Gold. Composition of plating is Cu-Ni-Au.	 Au 0.06µm Ni 2-7µm Cu 15-30µm
ENEPIG	Electroless Nickel Electroless Palladium Immersion Gold. Composition of plating is Cu-Ni-Pd-Au.	 Au 0.06µm Pd 0.04µm Ni 0.15-7µm Cu 15-30µm
DIG	Direct Immersion Gold. Since Ni plating is omitted, used for fine pitch compared to ENIG. Composition of plating is Cu-Au.	 Au 0.06µm Cu 15-30µm
EPIG	Electroless Palladium Immersion Gold. Composition of plating is Cu-Pd-Au.	 Au 0.06µm Pd 0.04µm Cu 15-30µm

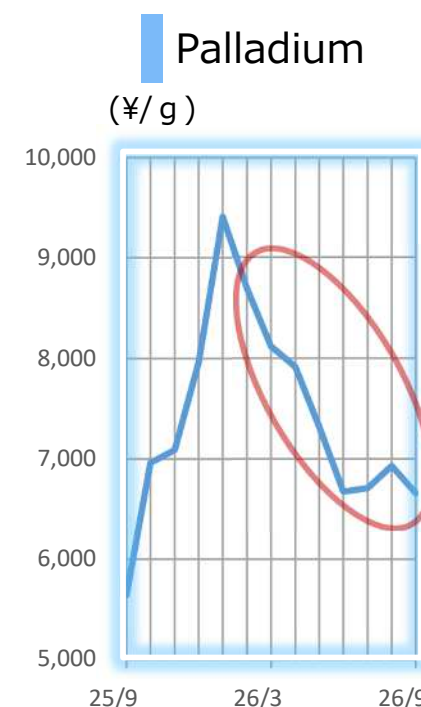
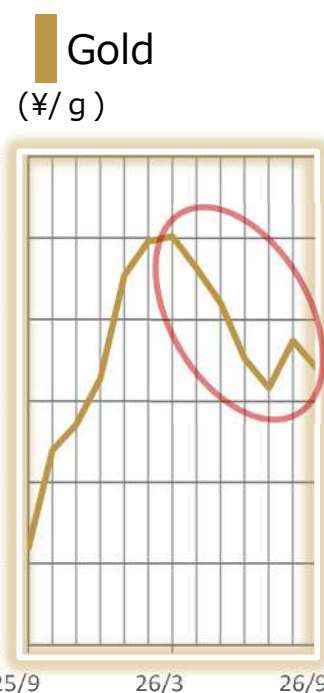
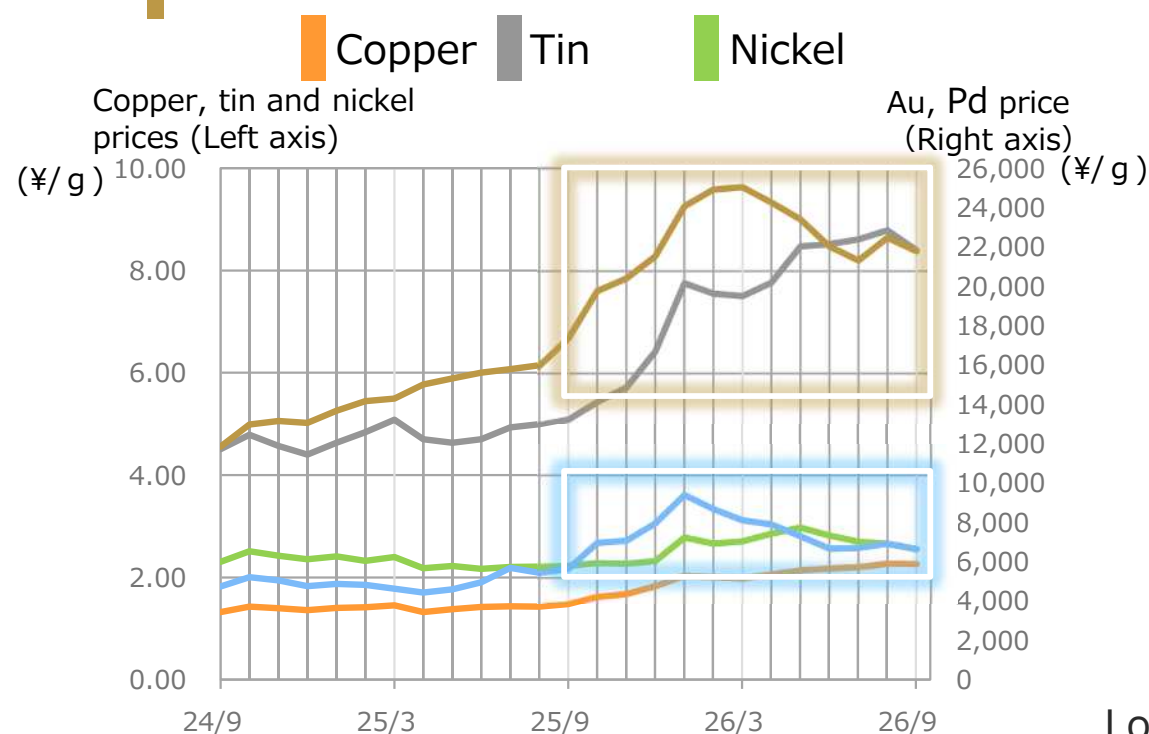
Au: gold, Pd: palladium, Ni: nickel, Cu: copper,
Micrometer (µm): one millionth of one meter

FY2027/3 External Environment of the 2nd quarter

Market Conditions in the Electronic Components Industry

- Despite strong generative AI and data center demand, general-purpose memory shortages constrained related equipment production and shipments, which fell short of expectations.
- Smartphone demand remained weak amid shortages of general-purpose memory and soaring prices, while higher PC prices offset lower shipments.
- Demand for industrial machinery remained solid, supported by capital investment in equipment for generative AI and data centers.
- The automotive segment was supported by demand in Japan and North America, but recovery varied by region and growth remained modest.

Historical Metal Prices



Long-term uptrend, but sharp decline first half

FY2027/3 2nd Quarter Financial Summary (cumulative)

Overview of Our Financial Results: Revenue Increased, Profit Decreased

- Net sales: Net sales increased 57.6% year on year, supported by solid demand across a broad range of markets, including generative AI, industrial machinery, and consumer applications. This growth was achieved despite constraints such as shortages of general-purpose memory, and was also boosted by higher precious metal prices.*1
- Operating profit: Operating profit fell 80.5% year on year, reflecting upfront investments in human capital and R&D, as well as a one-time factor from lower precious metal prices in the first half.*2
- Net profit: Net profit increased 11.3% year on year, despite lower operating profit, mainly due to gains on the sale of specified investment shares.

(M ¥)	FY2026/3	FY2027/3			
	1H	1Q	2Q	1H	Increase/ Decrease ratio
Net sales	7,536	6,152	5,725	11,878	+57.6%
Operating profit	271	31	21	53	(80.5%)
Ordinary profit	378	122	46	169	(55.1%)
Net profit	624	88	606	694	+11.3%
Net profit per share (Yen)	108.04	15.25	104.26	119.60	—

Noble Metal Prices (Monthly Average, per Gram)

※1 : YoY (Sep 2025 → Sep 2026)

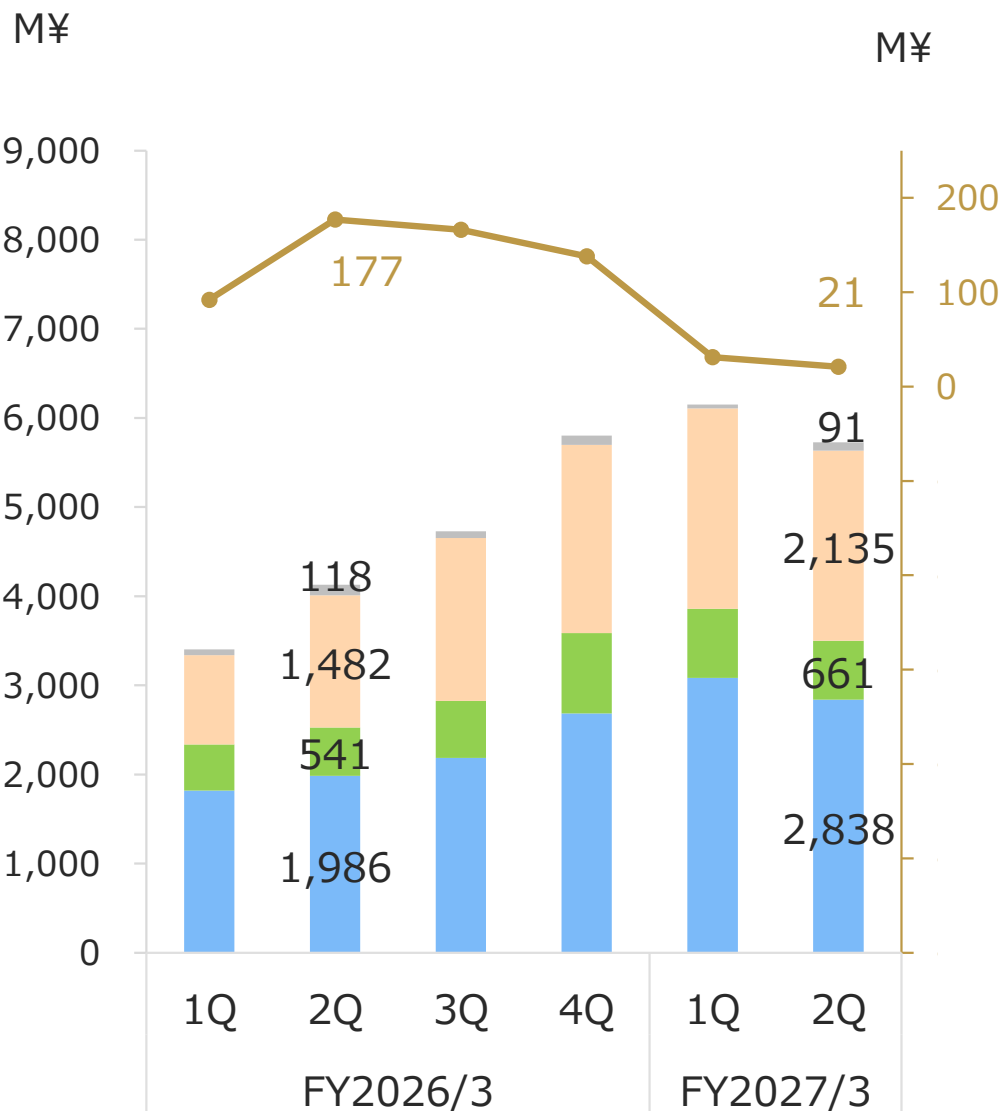
Gold: ¥17,380 → ¥21,800 (+25%) Palladium: ¥5,642 → ¥6,657 (+18%)

※2 : vs Mar2026 (Mar 2026 → Sep 2026)

Gold: ¥25,047 → ¥21,800 (-13%) Palladium: ¥8,116 → ¥6,657 (-18%)

Net sales and operating profit (Quarterly basis)

■ PCB・PKG
■ Lead Frame
■ Connector
■ Other
—●— Operating profit

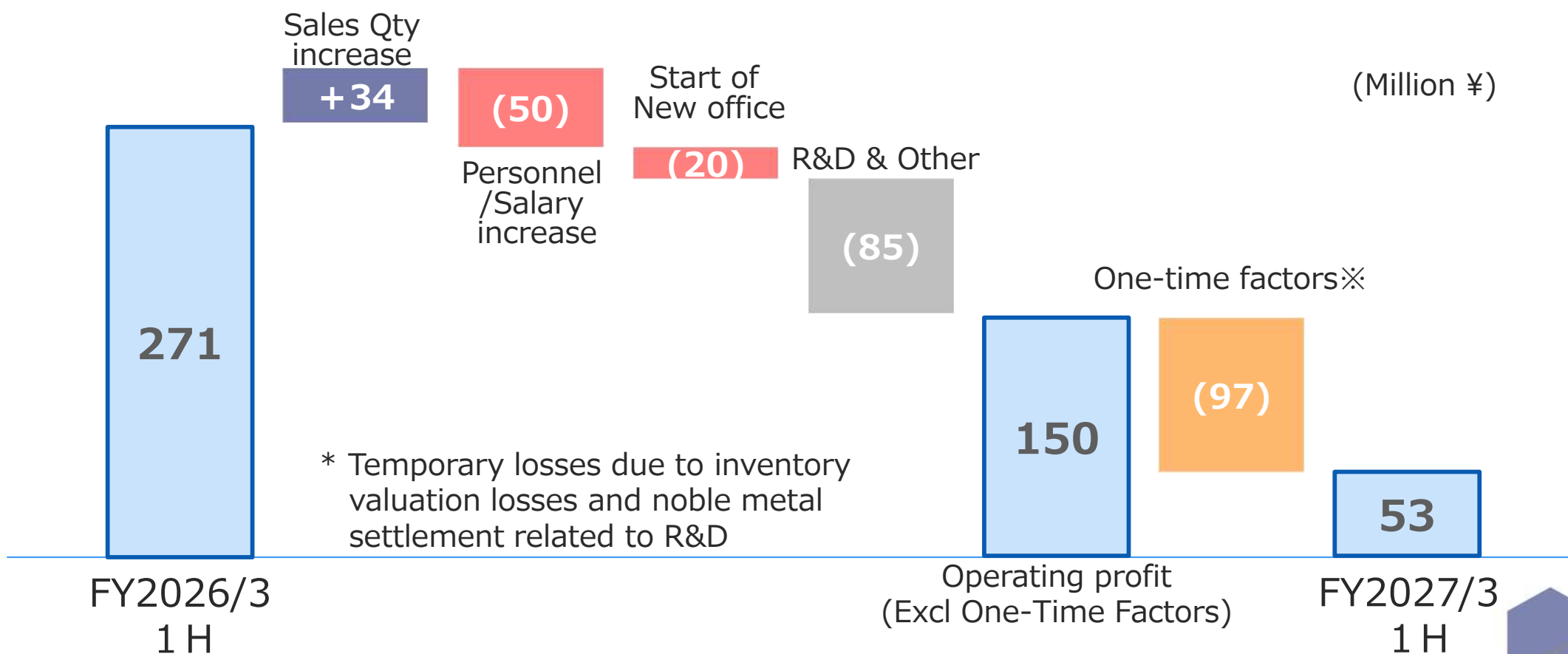


Overview by Category

- **Plating chemicals for printed circuit boards and semiconductor substrates**
 Despite weaker demand for low-end PCBs for PCs and smartphones, high-end PCBs exceeded expectations, while AI server package substrates remained strong. Higher noble metal prices also contributed to increased net sales.
- **Plating chemicals for connectors**
 Demand for smartphones remained flat, while automotive demand recovered due to increasing electrification. Stronger demand for generative AI-related industrial equipment also contributed to higher net sales.
- **Plating chemicals for lead frame**
 Strong demand for AI servers, along with solid automotive and industrial equipment demand and higher noble metal prices, contributed to increased net sales.

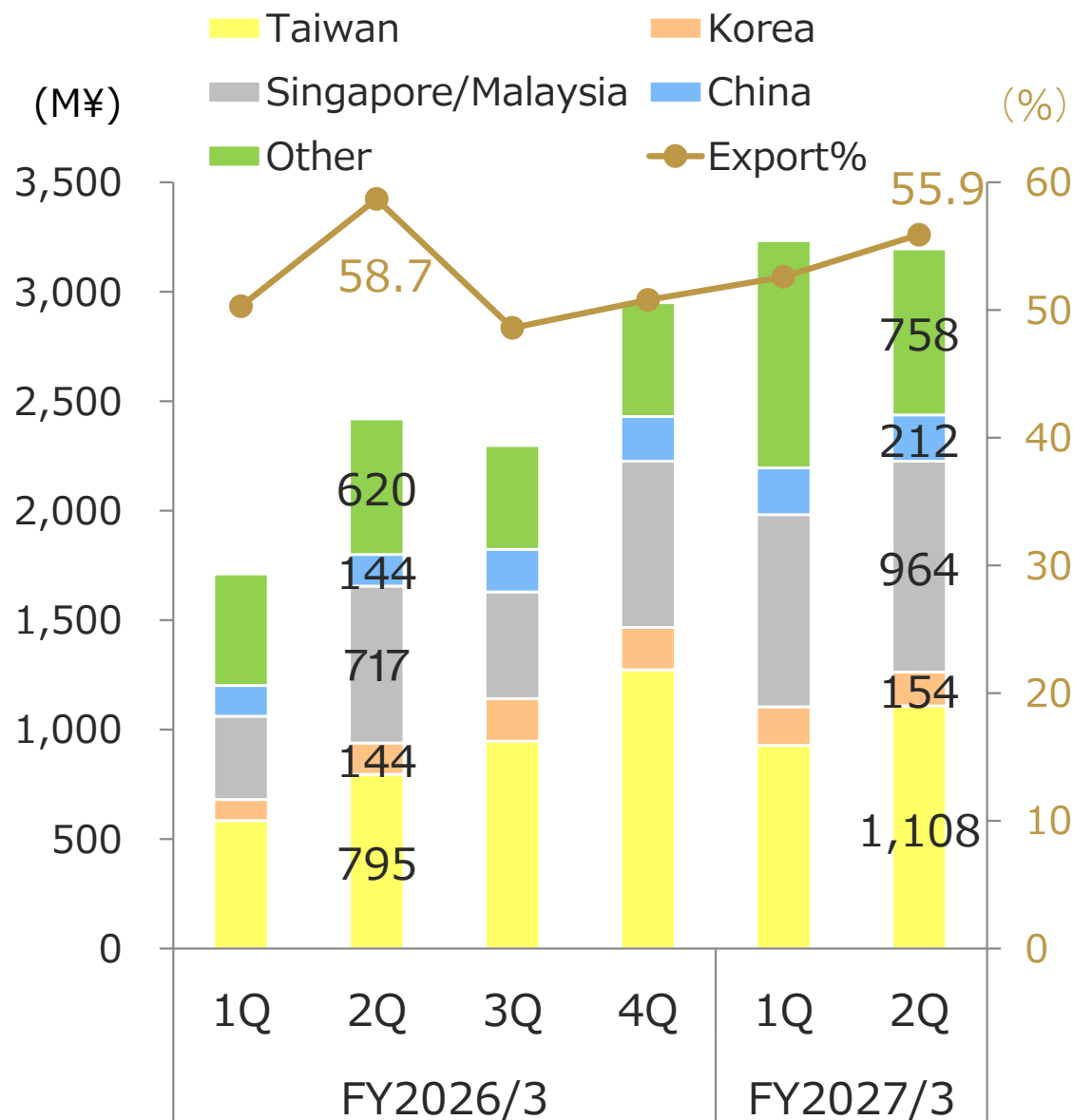
YoY Operating profit breakdown

- AI-related memory demand remained firm, but shortages of components, including general-purpose memory, weighed on memory-substrate sales. Demand for connectors, PCBs, and lead frames also remained firm, supported by demand in the smartphone, industrial equipment, and consumer markets, slightly lifting overall sales volume.
- Operating profit declined due to planned upfront investments in human capital and R&D, as well as one-time factors associated with lower noble metal prices.



Note: The Company minimizes the impact of exchange rate fluctuations through forward exchange contracts.

Net Sales by Export Regions (Quarterly basis)



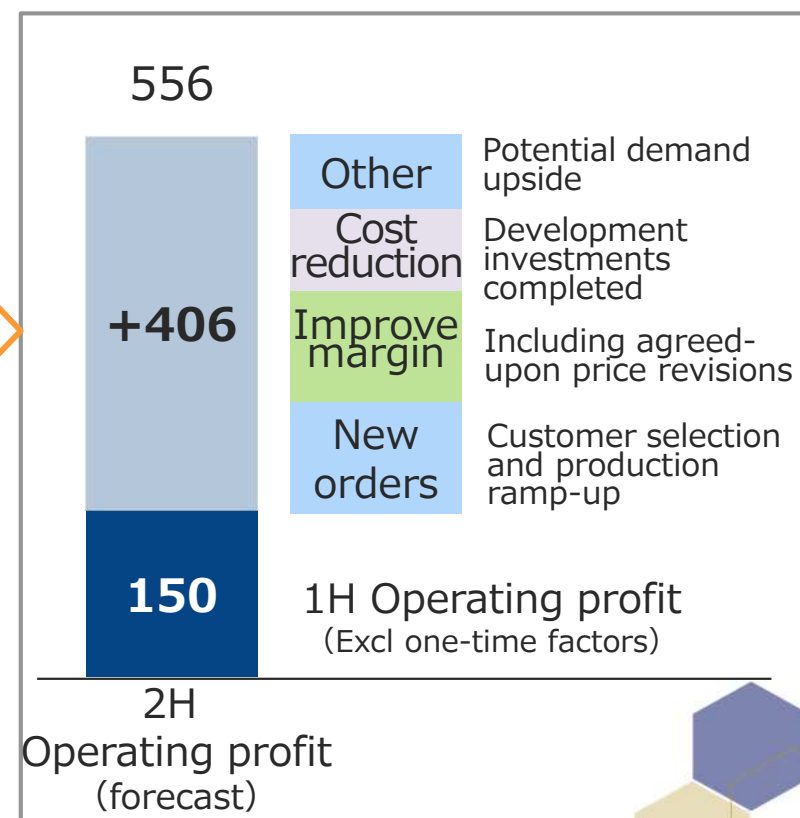
Reason for Increase/Decrease

- Taiwan**
 Strong demand for optical communication modules for AI servers and lead frames for industrial machinery and automotive applications, together with higher noble metal prices, boosted net sales.
- Singapore/Malaysia**
 Lead-frame demand for industrial machinery showed signs of recovery, while demand for package applications for PCs and AI servers remained strong. Higher noble metal prices also contributed to increased net sales.
- Other**
 Revenue increased on stronger demand in the Philippines for package applications for PCs and servers.

Outlook for the Fiscal Year Ending March 2027

- Although the recovery in some consumer demand remains gradual due to general-purpose memory supply constraints, AI-related demand remains strong.
- We will continue investing in human capital and R&D to strengthen our foundation for medium- to long-term growth.
- The disposal of the Specified Investment Shares scheduled for sale this fiscal year is progressing largely as planned.
- Despite lingering noble metal price impacts, stronger orders, price revisions, and cost efficiencies are expected to support the second half. The full-year forecast is unchanged.

	2027/3		
(M¥)	Initial Forecast	1 H Result	2H Forecast
Net sales	24,000	11,878	12,122
Operating profit	610	53	556
Ordinary profit	800	169	630
Gain on sale of investment	2,100	770	1,329
Net profit	2,170	694	1,475
Dividend per share (Yen)	230	115	115



Progress in sales of Specified Investment Shares

- The Company aims to reduce Specified Investment Shares to below 20% of net assets during the FY2026/3–FY2028/3 Medium-term Management Plan period.
- The market value of Specified Investment Shares increased from the previous fiscal year-end due to a significant rise in the share prices of certain holdings.
- We have been proceeding with the disposal of Specified Investment Shares in accordance with the plan established at the beginning of this fiscal year.

	2025 Sep	2025 Dec	2026 Mar	2026 Jun	2026 Sep
Amount sold ※ (M¥)	493	933	315	—	906
Market value of shares held (M¥)	8,416	9,308	10,743	17,956	14,885
Net assets (M¥)	15,566	16,659	18,064	22,315	20,957
Percentage of net assets (%)	54.1	55.9	59.5	80.5	71.0

※ Amount sold during the relevant period

Topic: Exhibition at SEMICON Taiwan 2026

- Established connections with Taiwanese companies at the forefront of global semiconductor technology to develop new customer relationships in the semiconductor sector.
- Raised awareness of JPC and its products while gaining insights into Taiwan's market and technology trends.

Event Overview

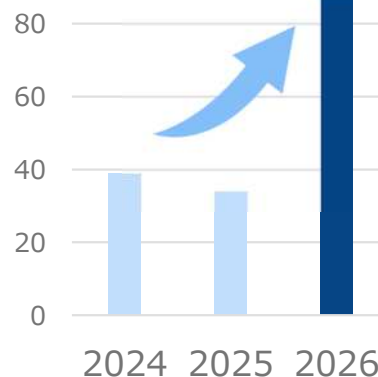
Date: September 2-4, 2026

Venue: TaiNEX Halls 1&2, Taipei

Scale: Over 1,300 exhibitors
(approx. 4,300 booths)

Exhibiting annually
since 2024

New Opportunities Created



2.5x
YoY

Scenes from our booth



Scenes from our technical presentation



Presented Our Noble Metal Plating: From Optical Semiconductors to Advanced AI Packages

- ✓ Advanced Cyanide-free Au Plating Technologies for Compound Semiconductor Applications

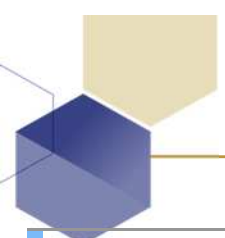
Thickness Uniformity, Via-hole Filling Performance, and Surface Smoothness
(For GaAs, GaN, InP, etc.) (Surface Roughness: $S_a < 20 \text{ nm}$)

- ✓ Plating Technologies for Advanced AI Accelerator Packaging Applications

Proposing Au and Pd Plating Technologies with Crystal Structure Control for Advanced Applications

(High Hardness for Au Plating, Improved Barrier Performance for Pd Plating)

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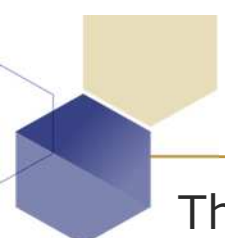
Appendix: Company Introduction

History

- July 1971 Establishment of JAPAN PURE CHEMICAL CO.,LTD.
- November 1999 Implementation of MBO
- December 2002 JASDAQ market listing
- March 2004 Listing on TSE Second Section
- March 2005 Listing on TSE First Section
- February 2019 Establishment of General incorporated foundation, JPC Scholarship Foundation
- April 2020 Certification as public interest incorporated foundation, JPC Scholarship Foundation
- April 2022 Moved to the Prime Market on TSE
- March 2026 Narimasu Office Established

Business Summary

- Fine chemical company supplying electronic materials which support development of the electronic components industry
- Top-class share in the worldwide market by narrowing the business targets to noble metal plating process
- Construct sales and technical support systems that can respond quickly to the rapidly changing industry
- Fab-light company that does not have large-scale manufacturing plants
- Provide technology to minimize the amount of noble metals used for connecting electronic components and contribute to effective use of mineral resources



Disclaimer

The materials used in the preparation of forecasts of results and predictions are based upon predicted trends in the industries related to the Company's operations. Accordingly, economic conditions both in Japan and overseas, fluctuations in exchange rates and other factors may influence forecasts of results. The predictions and forecasts made are based upon the information available as of September 30 2026.

There are a number of factors that cannot be predicted with certainty that may have an influence on these forecasts, including market conditions, competitors' actions, the performance of newly introduced products and services, and the global IT market and related markets. Accordingly, actual results may vary significantly from the forecasts presented in this document.

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Corporate Planning Division

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